CLAIMS:

1. A printed circuit board, comprising:

a plurality of conductive layers, wherein one of said plurality of conductive layers is a first layer, wherein one of said plurality of conductive layers is a second layer;

two or more vias interconnecting two or more conductive layers of said plurality of conductive layers, wherein a first of said two or more vias is part of a signal path configured to carry a signal from said first layer to said second layer, wherein a second of said two or more vias is part of a reference path configured to carry said signal from a third layer to a fourth conductive layer, wherein said fourth conductive layer returning said signal to a source; and

an electrical component embedded in said second of said two or more vias between two conductive layers of said plurality of conductive layers.

2. The printed circuit board as recited in claim 1, wherein said electrical component is a capacitor.

3. The printed circuit board as recited in claim 1, wherein said second of said two or more vias is a via adjacent to said first via of said two or more vias.

4. The printed circuit board as recited in claim 1, wherein said electrical component has a cylindrical configuration.

5. The printed circuit board as recited in claim 1, wherein a diameter from one end of said electrical component changes to an other end of said electrical component, wherein said second via of said two or more vias is configured so that one end of said second via of said two or more vias changes in diameter to an other end of said second via of said two or more vias.

6. The printed circuit board as recited in claim 5, wherein said electrical component is embedded between the two conductive layers of said plurality of conductive layers within said printed circuit board by adjusting the diameter of said electrical component and the diameter of said second via of said two or more vias.

7. The printed circuit board as recited in claim 1, wherein said electrical component has a greater diameter in a center than at ends of said electrical component, wherein each end of said electrical component has a conductive cap which is tinned.

8. The printed circuit as recited in claim 1, wherein said electrical component is packaged as a pin, wherein each end of said electrical component is soldered to said two conductive layers of said plurality of conductive layers within said printed circuit board.

9. The printed circuit as recited in claim 1, wherein said second layer is configured to carry said signal to a load, wherein said third layer is configured to return said signal from said load.

10. A printed circuit board, comprising:

a plurality of conductive layers;

two or more vias interconnecting two or more conductive layers of said plurality of conductive layers; and

an electrical component embedded in a particular via between two conductive layers of said plurality of conductive layers.

11. The printed circuit board as recited in claim 10, wherein said electrical component is a two terminal electrical component.

12. The printed circuit board as recited in claim 10, wherein said electrical component is a capacitor.

13. The printed circuit board as recited in claim 10, wherein said electrical component is a resistor.

14. The printed circuit board as recited in claim 10, wherein said electrical component is an inductor.

15. The printed circuit board as recited in claim 10, wherein said electrical component is a diode.

16. The printed circuit board as recited in claim 10, wherein said electrical component has a cylindrical configuration.

17. The printed circuit board as recited in claim 10, wherein a diameter from one end of said electrical component changes to an other end of said electrical component, wherein said particular via is configured so that one end of said particular via changes in diameter to an other end of said particular via.

18. The printed circuit board as recited in claim 17, wherein said electrical component is embedded between two conductive layers of said plurality of conductive layers by adjusting the diameter of said electrical component and the diameter of said particular via.

19. The printed circuit board as recited in claim 10, wherein said electrical component has a greater diameter in a center than at ends of said electrical component, wherein each end of said electrical component has a conductive cap which is tinned.

20. The printed circuit as recited in claim 10, wherein said electrical component is packaged as a pin, wherein each end of said electrical component is soldered to said two conductive layers of said plurality of conductive layers.

21. A method for reducing impedance within a reference path in a printed circuit board comprising the steps of:

forming said printed circuit board comprising a plurality of conductive layers, wherein one of said plurality of conductive layers is a first layer, wherein one of said plurality of conductive layers is a second layer, wherein said printed circuit board further comprises two or more vias interconnecting two or more conductive layers of said plurality of conductive layers, wherein a first of said two or more vias is part of a signal path configured to carry said signal from said first layer to said second layer, wherein a second of said two or more vias is part of a reference path configured to carry said signal from a third layer to a fourth conductive layer; and

embedding an electrical component in said second of said two or more vias between two conductive layers of said plurality of conductive.

22. The method as recited in claim 21, wherein said electrical component is a capacitor.

23. The method as recited in claim 21, wherein said second via of said two or more vias is a via adjacent to said first via of said two or more vias.

24. The method as recited in claim 21, wherein said electrical component has a cylindrical configuration.

25. The method as recited in claim 21, wherein a diameter from one end of said electrical component changes to an other end of said electrical component, wherein said second via of said two or more vias is configured so that one end of said second via of said two or more vias changes in diameter to an other end of said second via of said two or more vias.

26. The method as recited in claim 25 further comprising the step of:

embedding said electrical component between two conductive layers of said plurality of conductive layers within said printed circuit board by adjusting the diameter of said electrical component and the diameter of said second via of said two or more vias.

27. The method as recited in claim 21, wherein said electrical component has a greater diameter in a center than at ends of said electrical component, wherein each end of said electrical component has a conductive cap which is tinned.

28. The method as recited in claim 21, wherein said electrical component is packaged as a pin, wherein each end of said electrical component is soldered to said two conductive layers of said plurality of conductive layers within said printed circuit board.

29. The method as recited in claim 21, wherein said second layer is configured to carry said signal to a load, wherein said third layer is configured to return said signal from said load.

30. A method for saving space in a printed circuit board comprising the steps of:

forming said printed circuit board comprising a plurality of conductive layers, wherein said printed circuit board further comprises two or more vias interconnecting two or more conductive layers of said plurality of conductive layers; and

embedding an electrical component in a particular via between two conductive layers of said plurality of conductive layers.

31. The method as recited in claim 30, wherein said electrical component is a two terminal electrical component.

32. The method as recited in claim 30, wherein said electrical component is a capacitor.

33. The method as recited in claim 30, wherein said electrical component is a resistor.

34. The method as recited in claim 30, wherein said electrical component is an inductor.

35. The method as recited in claim 30, wherein said electrical component is a diode.

36. The method as recited in claim 30, wherein said electrical component has a cylindrical configuration.

37. The method as recited in claim 30, wherein a diameter from one end of said electrical component changes to an other end of said electrical component, wherein said particular via is configured so that one end of said particular via changes in diameter to an other end of said particular via.

38. The method as recited in claim 37, wherein said electrical component is embedded between two conductive layers of said plurality of conductive layers by adjusting the diameter of said electrical component and the diameter of said particular via.

39. The method as recited in claim 30, wherein said electrical component has a greater diameter in a center than at ends of said electrical component, wherein each end of said electrical component has a conductive cap which is tinned.

40. The method as recited in claim 30, wherein said electrical component is packaged as a pin, wherein each end of said electrical component is soldered to said two conductive layers of said plurality of conductive layers.